

P30449.A02

IN THE ABSTRACT

Please replace the Abstract contained in the application with the following amended Abstract.

### **Abstract of the Disclosure**

An electronic component mounting method comprising: supplying an unhardened reinforcing resin ~~(3, 15)~~ on a circuit substrate (4); supplying a solder paste (4) on bond areas of the circuit substrate (4) on which electrodes ~~(5a, 6a)~~ of the electronic components ~~(5, 6)~~ are to be bonded; placing the electronic components ~~(5, 6)~~ on the circuit substrate (4); and heating and then cooling the circuit substrate (4) with the reinforcing resin ~~(3, 15)~~, the solder paste (4), and the electronic components ~~(5, 6)~~ carried thereon. The mounting method enables mounting of components with high joint reliability, while incorporating the conventional surface mount process steps. The method may also be applied to the mounting of smaller electronic components with narrower pitch without deteriorating productivity or mounting quality.